12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20161102000A
Qualification of HANA Thailand as Additional Assembly and Test Site for Select SSOP Package Devices
Change Notification / Sample Request

Date: January 16, 2017
To: Newark/Farnell PCN

Dear Customer:

Revision A is to announce the addition of new devices that were not included on the original PCN notification.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20161102000A
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
PCA9306DCTR	null
PCA9306DCTT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20161102000A	PCN Date:	Jan 16, 2017
Title:	Qualification of HANA Thailand as Additional Assembly and Test Site for Select SSOP Package Devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Apr 16, 2017	Estimated Sample Availability:	Date Provided at Sample request

Change Type:					
☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Site
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Revision A is to announce the addition of new devices that were not included on the original PCN notification. These new devices are highlighted and **bolded** in the device list below. The expected first shipment date for these new devices will be 90 days from this notice for these newly added devices only.

Texas Instruments Incorporated is announcing the qualification of HANA Thailand as Additional Assembly and Test Site for select devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City
Hitachi	HTC	JPN	Kitatsugaru, Aomori
HANA Thailand	**HNT**	**THA**	**Ayutthaya**

Material Differences:

	Hitachi	HANA Thailand
Mount Compound	RZ241C	F400728
Mold compound	G600K	F450524

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
Hitachi	Assembly Site Origin (22L)	ASO: HTC
HANA Thailand	Assembly Site Origin (22L)	ASO: HNT

Sample product shipping label (not actual product label)

ASSEMBLY SITE CODES: HIT = T , HNT = H

Product Affected:

74AVCH2T45DCTRE4	SN74AUC2G240DCTR	SN74LVC2G02DCTRE4	SN74LVC3G04DCTRG4
74AVCH2T45DCTTE4	SN74AUC2G241DCTR	SN74LVC2G02DCTRG4	SN74LVC3G06DCTR
74LVC1G123DCTRE4	SN74AUC2G32DCTR	SN74LVC2G08DCTR	SN74LVC3G06DCTRE4
74LVC1G123DCTRG4	SN74AUC2G66DCTR	SN74LVC2G08DCTRE4	SN74LVC3G07DCTR
74LVC1G123DCTTE4	SN74AUC2G79DCTR	SN74LVC2G08DCTRG4	SN74LVC3G07DCTRG4
74LVC1G123DCTTG4	SN74AUC2G80DCTR	SN74LVC2G125DCTR	SN74LVC3G14DCTR
74LVC1G139DCTRE4	SN74AUC2G80DCTRG4	SN74LVC2G132DCTR	SN74LVC3G14DCTR-P
74LVC1G139DCTTE4	SN74AUC2G86DCTR	SN74LVC2G157DCTR	SN74LVC3G14DCTRE4
74LVC2G125DCTR-P2	SN74AUP1G99DCTR	SN74LVC2G157DCTR-P	SN74LVC3G14DCTRG4
74LVC2G125DCTRE4	SN74AUP1G99DCTT	SN74LVC2G157DCTRG4	SN74LVC3G17DCTR
74LVC2G125DCTRG4	SN74AVC2T45DCTR	SN74LVC2G240DCTR	SN74LVC3G17DCTRE4
74LVC2G132DCTRG4	SN74AVC2T45DCTRE4	SN74LVC2G32DCTR	SN74LVC3G17DCTRG4
74LVC2G157DCTRE4	SN74AVC2T45DCTT	SN74LVC2G32DCTRE4	SN74LVC3G34DCTR
74LVC2G240DCTRE4	SN74AVC2T45DCTTG4	SN74LVC2G32DCTRG4	SN74LVC3G34DCTR-P
LSF0102DCTR	SN74AVCH2T45DCTR	SN74LVC2G38DCTR	SN74LVC3G34DCTRG4
PCA9306DCTR	SN74AVCH2T45DCTT	SN74LVC2G66DCTR	SN74LVC3GU04DCTR
PCA9306DCTRE4	SN74LVC1404DCTR	SN74LVC2G66DCTRE4	SN74TVC3306DCTR
PCA9306DCTRG4	SN74LVC1G123DCTR	SN74LVC2G66DCTRG4	SN74TVC3306DCTRE4
PCA9306DCTT	SN74LVC1G123DCTT	SN74LVC2G79DCTR	TCA9406DCTR
PCA9306DCTTE4	SN74LVC1G139DCTR	SN74LVC2G80DCTR	TS5A2053DCTR
PCA9306DCTTG4	SN74LVC1G139DCTT	SN74LVC2G80DCTRG4	TS5A2053DCTRE4
SN74AUC2G00DCTR	SN74LVC1G29DCTR	SN74LVC2G86DCTR	TXS0102DCTR
SN74AUC2G00DCTRE4	SN74LVC1G99DCTR	SN74LVC2G86DCTRG4	TXS0102DCTRE4
SN74AUC2G02DCTR	SN74LVC1G99DCTRG4	SN74LVC2T45DCTR	TXS0102DCTT
SN74AUC2G08DCTR	SN74LVC1G99DCTT	SN74LVC2T45DCTRE4	TXS0102DCTTE4
SN74AUC2G08DCTRE4	SN74LVC2G00DCTR	SN74LVC2T45DCTT	TXS0102DCTTG4
SN74AUC2G08DCTRG4	SN74LVC2G00DCTRE4	SN74LVC2T45DCTTG4	
SN74AUC2G125DCTR	SN74LVC2G00DCTRG4	SN74LVC3G04DCTR	
SN74AUC2G126DCTR	SN74LVC2G02DCTR	SN74LVC3G04DCTRE4	

Qualification Report

New Package: DCT package qual at HNT

Approve Date 18-Oct-2016

Product Attributes

Attributes	Qual Device: PCA9306DCTR	Qual Device: TXS0102DCTR
Assembly Site	HNT	HNT
Package Family	SSOP	SSOP
Flammability Rating	UL 94 V-0	UL 94 V 0
Wafer Fab Supplier	SFAB	FFAB
Wafer Process	EPIC1ZS	A3C10TPI /P9785

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL1-260C:PCA9306DCTR, TXS0102DCTR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: PCA9306DCTR	Qual Device: TXS0102DCTR
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0
FLAM	Flammability (IEC 695-2-2)	--	-	3/15/0
FLAM	Flammability (UL 94V-0)	--	-	3/15/0
FLAM	Flammability (UL-1694)	--	-	3/15/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	3/231/0
LI	Lead Fatigue	Leads	-	3/66/0
LI	Lead Pull to Destruction	Leads	-	3/66/0
PD	Physical Dimensions	--	-	3/15/0
SD	Surface Mount Solderability	Pb Free	-	3/66/0
SD	Surface Mount Solderability	Pb	-	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0
WBP	Bond Pull	Wires	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report

A-T / Device Offload into HNT DCT package

Approve Date 19-Oct-2016

Product Attributes

Attributes	Qual Device: SN74LVC2G66DCTR	QBS Package Reference: TXS0102DCTR
Assembly Site	HNT	HNT
Package Family	SSOP	SSOP
Flammability Rating	UL 94 V-0	UL 94 V 0
Wafer Fab Supplier	FFAB	FFAB
Wafer Process	A3CTPI-8	A3C10TPI

- QBS: Qual By Similarity
- Qual Device SN74LVC2G66DCTR is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN74LVC2G66DCTR	QBS Package Reference: TXS0102DCTR
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0
FLAM	Flammability (IEC 695-2-2)	--	-	3/15/0
FLAM	Flammability (UL 94V-0)	--	-	3/15/0
FLAM	Flammability (UL-1694)	--	-	3/15/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0	3/231/0
LI	Lead Fatigue	Leads	-	3/66/0
LI	Lead Pull to Destruction	Leads	-	3/66/0
PD	Physical Dimensions	--	-	3/15/0
SD	Surface Mount Solderability	Pb Free	-	3/66/0
SD	Surface Mount Solderability	Pb	-	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0
WBP	Bond Pull	Wires	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
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- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com